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## (54) STRUCTURE OF SEMICONDUCTOR WIRING

## (57)Abstract:

PROBLEM TO BE SOLVED: To easily secure the tight adhesion between semiconductor wiring and a projecting electrode, by constituting a rewiring structure in which an original pad on a semiconductor chip is rewired on a new bonding pad at a different position in a three-layer structure and the metallic structure under the projecting electrode is constituted in a two-layer structure.

SOLUTION: In a rewiring metal depositing process, rewiring metals 5 are deposited in three steps in the order of Ni.V 6, Cu 7, and Ni.V 8 by the sputtering method. Then, in an Ni.V opening process, the uppermost Ni.V 8 of the metals 5 is etched and the Cu 7 is exposed in an Ni.V opening 9. Successively, in a rewiring forming process, a rewiring pattern 10 is formed by etching the Ni.V 8, Cu 7, and Ni.V 6 of the metals 5 and a new bonding pad 12 is formed by using the final polyimide film 11, so that the rewiring pattern 10 may be protected and the Ni.V opening 9 may be exposed. A solder bump 13 which is formed as a projecting electrode is formed on the new bonding pad 12.



## LEGAL STATUS

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